

Title (en)
SOLDER ALLOY

Title (de)
LÖTLEGIERUNG

Title (fr)
ALLIAGE DE SOUDURE

Publication
EP 1924394 A2 20080528 (EN)

Application
EP 06779198 A 20060824

Priority
• GB 2006003167 W 20060824
• US 71091705 P 20050824

Abstract (en)
[origin: WO2007023288A2] An alloy suitable for use in a ball grid array, the alloy comprising from 0.15 - 1.5 wt.% copper, from 0.1 - 4 wt.% silver, from 0 - 0.1 wt.% phosphorus, from 0 - 0.1 wt.% germanium, from 0 - 0.1 wt.% gallium, from 0 - 0.3 wt.% of one or more rare earth elements, from 0 - 0.3 wt.% indium, from 0 - 0.3 wt.% magnesium, from 0 - 0.3 wt.% calcium, from 0 - 0.3 wt.% silicon, from 0 - 0.3 wt.% aluminium, from 0 - 0.3 wt.% zinc, from 0 - 1 wt.% antimony, and at least one of the following elements from 0.02 - 0.3 wt% nickel, from 0.008 - 0.2 wt% manganese, from 0.01 - 0.3 wt% cobalt, from 0.005 - 0.3 wt% chromium, from 0.02 - 0.3 wt% iron, and from 0.008 - 0.1 wt% zirconium, and the balance tin, together with unavoidable impurities.

IPC 8 full level
B23K 35/26 (2006.01); **C22C 12/00** (2006.01)

CPC (source: EP KR)
B23K 35/26 (2013.01 - KR); **B23K 35/262** (2013.01 - EP); **C22C 12/00** (2013.01 - KR); **C22C 13/00** (2013.01 - EP); **H01L 2924/0002** (2013.01 - EP); **H05K 3/3436** (2013.01 - EP); **H05K 3/3463** (2013.01 - EP)

Citation (search report)
See references of WO 2007023288A2

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